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(54) **METHOD FOR MANUFACTURING DISPLAY  
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(71) Applicant: **Semiconductor Energy Laboratory  
Co., Ltd.**, Kanagawa-ken (JP)

(72) Inventors: **Yasutaka NAKAZAWA**, Tochigi (JP);  
**Naoto GOTO**, Tochigi (JP); **Kenichi  
OKAZAKI**, Atsugi (JP); **Takayuki  
OHIDE**, Isehara (JP)

(73) Assignee: **Semiconductor Energy Laboratory  
Co., Ltd.**, Kanagawa-ken (JP)

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(57) **ABSTRACT**

A method for manufacturing a novel display device that is highly convenient, useful, or reliable is to be provided. A first film is formed over a first electrode and a second electrode in a second step in the manufacturing method; a second film is formed over the first film in a third step; a third film is formed over the second film by a CVD method in a fourth step; part of the third film located above the second electrode is removed by an etching method to form a first layer overlapping with the first electrode in a fifth step; and part of the second film and part of the first film each located above the second electrode are removed by an etching method using the first layer to form a second layer and a first unit each overlapping with the first electrode in a sixth step.

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